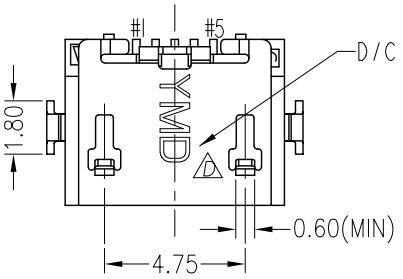
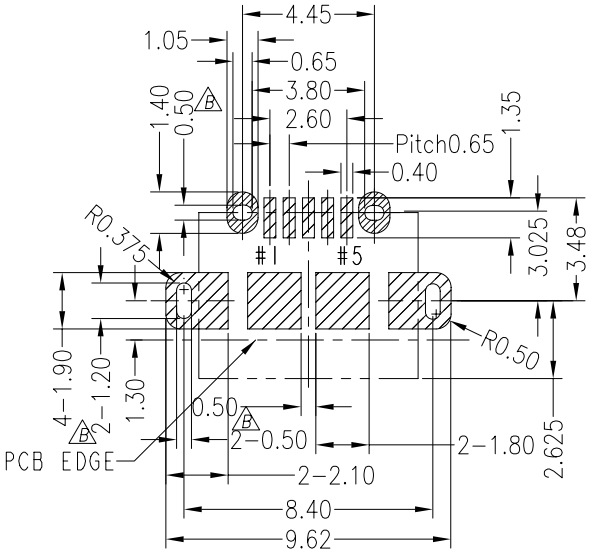
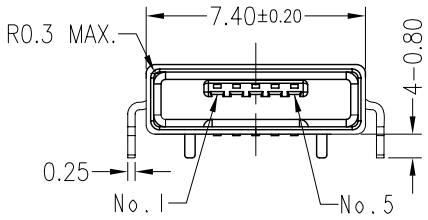
| REV. | ECN NO OR DESCRIPTION | REVISED | DATE |
|---|---|---|---|
| B | ECN:C110347 Modify layout dim | Longjiang | 2011.11.04 |
| C | ECN:C120039 UPDATE DRAWING | Daowen | 2012.2.20 |
| D | ECN:C120097 UPDATE DRAWING | Daowen | 2012.05.08 |

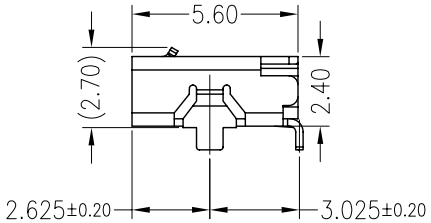


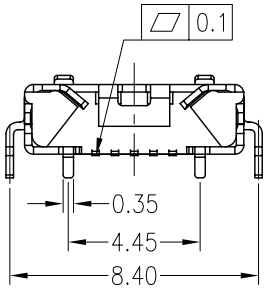



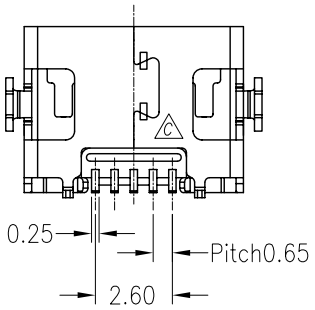

RECOMMENDED PCB LAYOUT

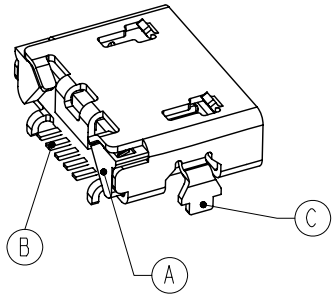
TOP VIEW, TOL ±0.05




SPECIFICATIONS:

1. ELECTRICAL CHARACTERISTICS:
   1-1. RATING: 2A (PIN1/5), 0.5A (PIN2/3/4)
   1-2. CONTACT RESISTANCE: 30mΩ MAX.(INITIAL) 40mΩ MAX.(FINAL)
   1-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
   1-4. INSULATION RESISTANCE: 100M MIN. MEASURED BY 500 VDC
2. MECHANICAL CHARACTERISTICS:
   2-1. INSERTION FORCE : 3.6 KGF (MAX)
   2-2. WITHDRAWAL FORCE : 0.8 KGF(MIN)
3. LIFE TEST: 10,000 CYCLES .
4. TO CONFORM TO THE SINGATRON HSF SPEC.
5. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
6. HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
7. FOR REFLOW SOLDERING LEAD-FREE PROCESS.
8. SOLDER HEAT RESISTANCE REFLOW SOLDERING 260°C 10SECS.
9. PLUG INTERFACE DIMENSIONS COMFORM TO USB2.0 SPEC.
10. PACKAGING: TAPE & REEL.

| NO | DESCRIPTION | QTY | MATERIAL | PLATING & COLOR |
|---|---|---|---|---|
| C | SHELL | 1 | STAINLESS STEEL 0.25T | MATTE TIN |
| B | CONTACT | 5 | COPPER ALLOY 0.15T | 30u" Au ON CONTACT AREA<br>GOLD FLASH ON SOLDER AREA |
| A | HOUSING | 1 | HI-TEMP. THERMO-PLASTIC UL94V-0 | GRAY |

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: X :±0.5 X.X :±0.3 X.XX :±0.2

ANGLES: X :±2° X.X :±1°

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

| | | | |
|---|---|---|---|
| TITLE | MICRO USB AB TYPE RECEPTACLE | | |
| DWN | Daowen 2012.5.8 | PART NO. 2UB2002-004111F | |
| CHKD | ZJZ 2012.5.8 | SCALE 5:1 | UNIT: mm |
| APVD | LIAO 2012.5.8 | SIZE: A3 | SHEET:1 OF 1 REV:D |

CUSTOMER COPY

文件編號 RD-06-043-A